

CMS35N04V8-HF

N-Channel
RoHS Device
Halogen Free

Features

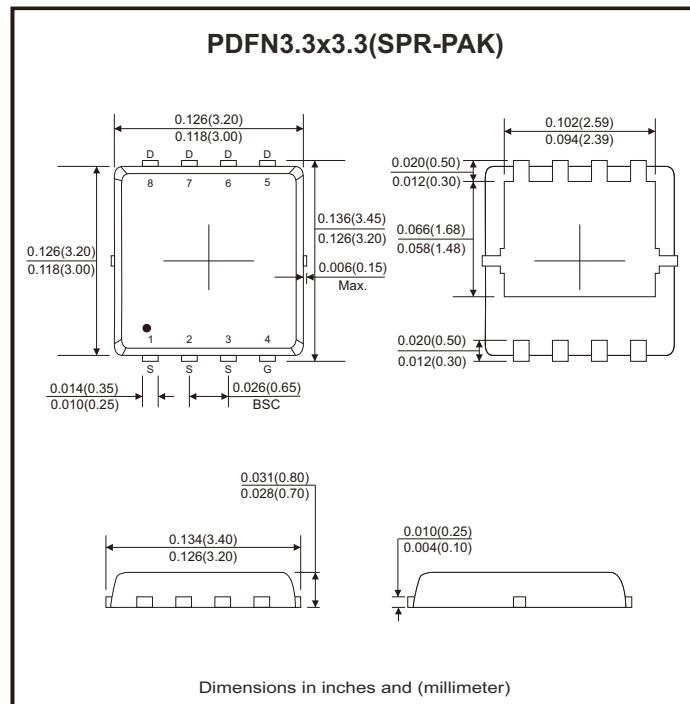
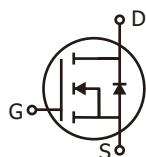
- Advanced DMOS trench technology.
- Fast switching.
- Improve dv/dt capability.
- Green device available.
- 100% EAS guaranteed.

Mechanical data

- Case: PDFN3.3x3.3/SPR-PAK standard package, molded plastic.

Circuit diagram

- G : Gate
- S : Source
- D : Drain



Maximum Ratings

Parameter	Conditions	Symbol	Value	Unit
Drain-source voltage		V_{DS}	40	V
Gate-source voltage		V_{GS}	± 20	V
Continuous drain current (Note 1)	$I_D @ T_c = 25^\circ C$		35	A
	$I_D @ T_c = 100^\circ C$		22.1	
Pulsed drain current (Note 1, 2)		I_{DM}	140	A
Total power dissipation (Note 4)	$P_D @ T_c = 25^\circ C$		44	W
	$P_D @ T_A = 25^\circ C$		2	
Single pulse avalanche energy, $L=0.1mH$ (Note 3)		E_{AS}	61	mJ
Single pulse avalanche current, $L=0.1mH$ (Note 3)		I_{AS}	35	A
Operating junction temperature range		T_J	-55 to +150	°C
Storage temperature range		T_{STG}	-55 to +150	°C
Thermal resistance junction-ambient (Note 1)	Steady state	$R_{\theta JA}$	62.5	°C/W
Thermal resistance junction-case (Note 1)	Steady state	$R_{\theta JC}$	2.8	°C/W

Electrical Characteristics (at $T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-source breakdown voltage	BV_{DSS}	$\text{V}_{\text{GS}} = 0\text{V}, \text{I}_D = 250\mu\text{A}$	40			V
Gate threshold voltage	$\text{V}_{\text{GS(th)}}$	$\text{V}_{\text{DS}} = \text{V}_{\text{GS}}, \text{I}_D = 250\mu\text{A}$	1.2	1.7	2.5	
Gate-source leakage current	I_{GSS}	$\text{V}_{\text{GS}} = \pm 20\text{V}$			± 100	nA
Drain-source leakage current ($T_J=25^\circ\text{C}$)	I_{DSS}	$\text{V}_{\text{DS}} = 40\text{V}, \text{V}_{\text{GS}} = 0\text{V}$			1	μA
Drain-source leakage current ($T_J=85^\circ\text{C}$)		$\text{V}_{\text{DS}} = 32\text{V}, \text{V}_{\text{GS}} = 0\text{V}$			10	
Static drain-source on-resistance (Note 2)	$\text{R}_{\text{DS(on)}}$	$\text{V}_{\text{GS}} = 10\text{V}, \text{I}_D = 10\text{A}$		7.5	9	$\text{m}\Omega$
		$\text{V}_{\text{GS}} = 4.5\text{V}, \text{I}_D = 8\text{A}$		11	13.5	
Total gate charge (Note 2)	Q_g	$\text{I}_D = 8\text{A}, \text{V}_{\text{DS}} = 20\text{V}, \text{V}_{\text{GS}} = 10\text{V}$		19.7		nC
Gate-source charge	Q_{gs}			2.8		
Gate-drain ("miller") charge	Q_{gd}			5.1		
Turn-on delay time (Note 2)	$\text{t}_{\text{d(on)}}$	$\text{V}_{\text{DS}} = 15\text{V}, \text{V}_{\text{GS}} = 10\text{V}$ $\text{I}_D = 1\text{A}, \text{R}_G = 3.3\Omega$		13.2		nS
Rise time	t_r			2.2		
Turn-off delay time	$\text{t}_{\text{d(off)}}$			72		
Fall time	t_f			4.5		
Input capacitance	C_{iss}	$\text{V}_{\text{GS}} = 0\text{V}, \text{V}_{\text{DS}} = 25\text{V}, \text{f} = 1\text{MHz}$		1220		pF
Output capacitance	C_{oss}			130		
Reverse transfer capacitance	C_{rss}			55		
Gate resistance	R_g	$\text{f} = 1\text{MHz}$		2.2		Ω
Source-drain diode						
Diode forward voltage (Note 2)	V_{SD}	$\text{I}_s = 10\text{A}, \text{V}_{\text{GS}} = 0\text{V}, \text{T}_J=25^\circ\text{C}$			1.2	V
Continuous source current (Note 1, 6)	I_s	$\text{V}_G = \text{V}_D = 0\text{V}$, Force current			35	A
Pulsed source current (Note 2, 6)	I_{SM}				70	A
Guaranteed avalanche characteristics						
Single pulse avalanche energy (Note 5)	EAS	$\text{V}_{\text{DD}} = 25\text{V}, \text{L}=0.1\text{mH}, \text{I}_{\text{AS}} = 18\text{A}$	16.2			mJ

- Notes:
1. The data tested by surface mounted on a 1 inch² FR-4 board with 2 oz copper.
 2. The data tested by pulsed, pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
 3. The EAS data shows max. rating. The test condition is $\text{V}_{\text{DD}}=25\text{V}, \text{V}_{\text{GS}}=10\text{V}, \text{L}=0.1\text{mH}, \text{I}_{\text{AS}}=35\text{A}$.
 4. The power dissipation is limited by 150°C junction temperature.
 5. The min. value is 100% EAS tested guarantee.
 6. The data is theoretically the same as ID and IDM, in real applications, should be limited by total power dissipation.

Rating and Characteristic Curves (CMS35N04V8-HF)

Fig.1 - Drain Current vs. T_c

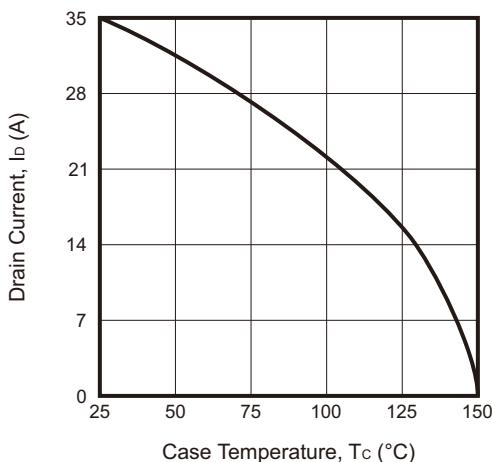


Fig.2 - Gate Charge Characteristics

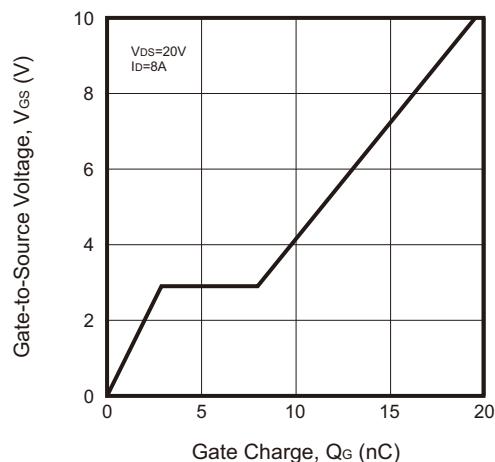


Fig.3 - Normalized $V_{GS(th)}$ vs. T_J

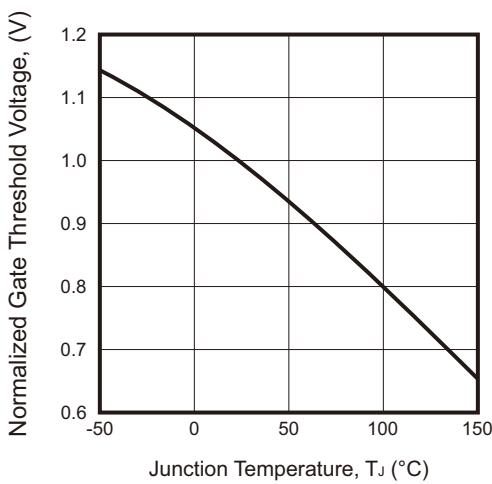


Fig.4 - Normalized $R_{DS(ON)}$ vs. T_J

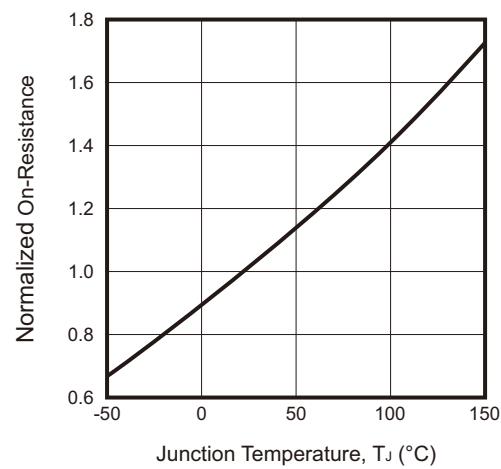
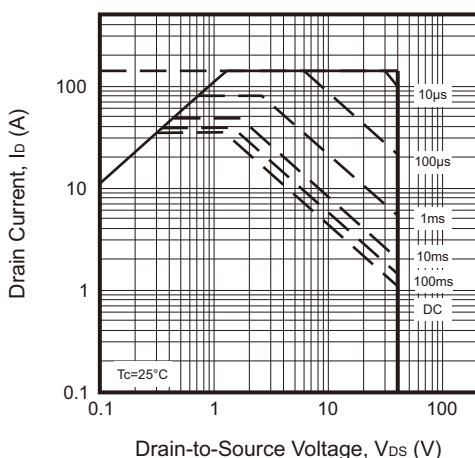


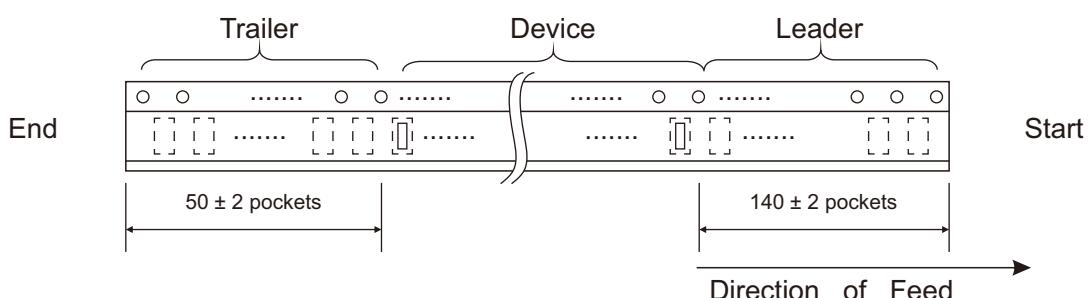
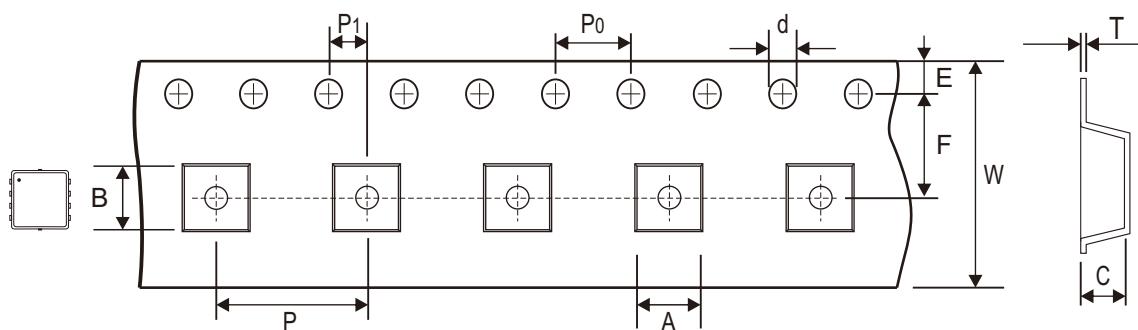
Fig.5 - Safe Operating Area



Company reserves the right to improve product design , functions and reliability without notice.

REV:A

Reel Taping Specification



SPR-PAK	SYMBOL	A	B	C	d	D	D1	D2
	(mm)	3.55 ± 0.10	3.55 ± 0.10	$1.10 + 0.10$ - 0.05	$1.50 + 0.10$ - 0.00	330.00 ± 1.00	$178.00 + 0.00$ - 2.00	13.00 min.
	(inch)	0.140 ± 0.004	0.140 ± 0.004	$0.043 + 0.004$ - 0.002	$0.059 + 0.004$ - 0.000	12.992 ± 0.039	$7.008 + 0.000$ - 0.079	0.512 min.

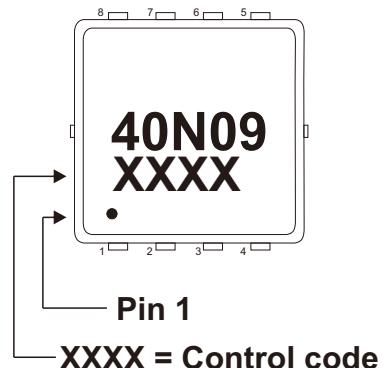
SPR-PAK	SYMBOL	E	F	P	P0	P1	T	W	W1
	(mm)	1.75 ± 0.10	5.50 ± 0.05	8.00 ± 0.10	4.00 ± 0.10	2.00 ± 0.05	0.30 ± 0.05	$12.00 + 0.30$ - 0.10	18.40 ref.
	(inch)	0.069 ± 0.004	0.217 ± 0.002	0.315 ± 0.004	0.157 ± 0.004	0.079 ± 0.002	0.012 ± 0.002	$0.472 + 0.012$ - 0.004	0.724 ref.

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REV:A

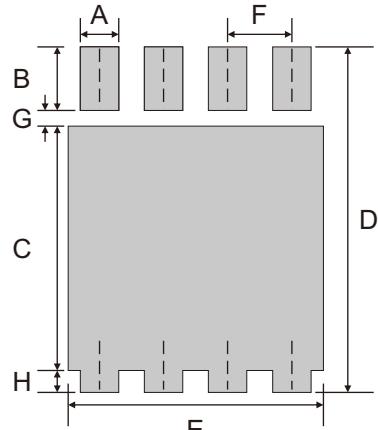
Marking Code

Part Number	Marking Code
CMS35N04V8-HF	40N09



Suggested PAD Layout

SIZE	SPR-PAK (PDFN3.3x3.3)	
	(mm)	(inch)
A	0.40	0.016
B	0.60	0.024
C	2.35	0.093
D	3.55	0.140
E	2.80	0.110
F	0.65	0.026
G	0.35	0.014
H	0.25	0.010



Note: 1. The pad layout is for reference purposes only.

Standard Packaging

Case Type	REEL PACK	
	REEL (pcs)	Reel Size (inch)
SPR-PAK (PDFN3.3x3.3)	3000	13